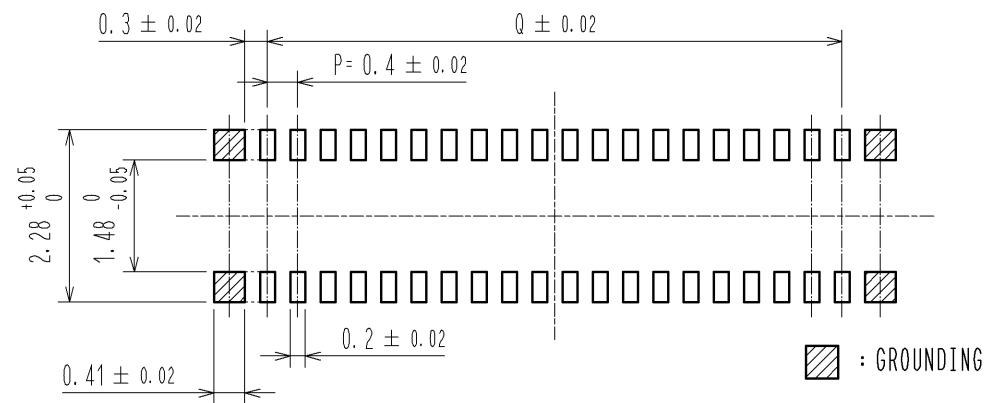
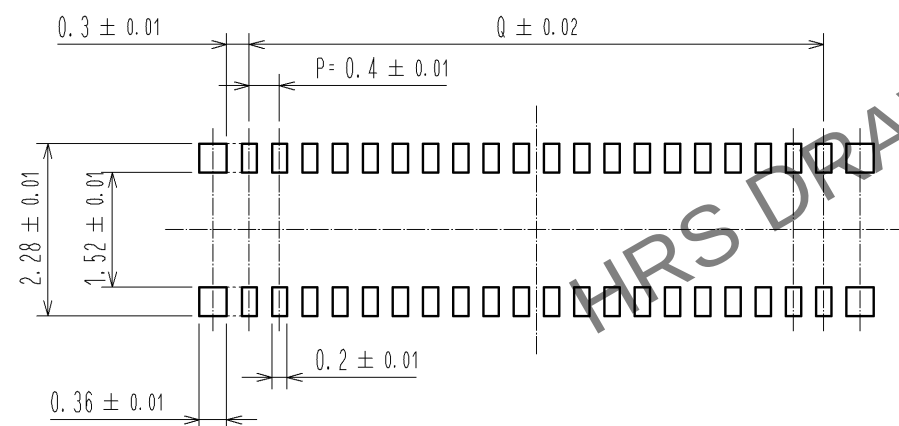


◆ RECOMMENDED PCB LAYOUT



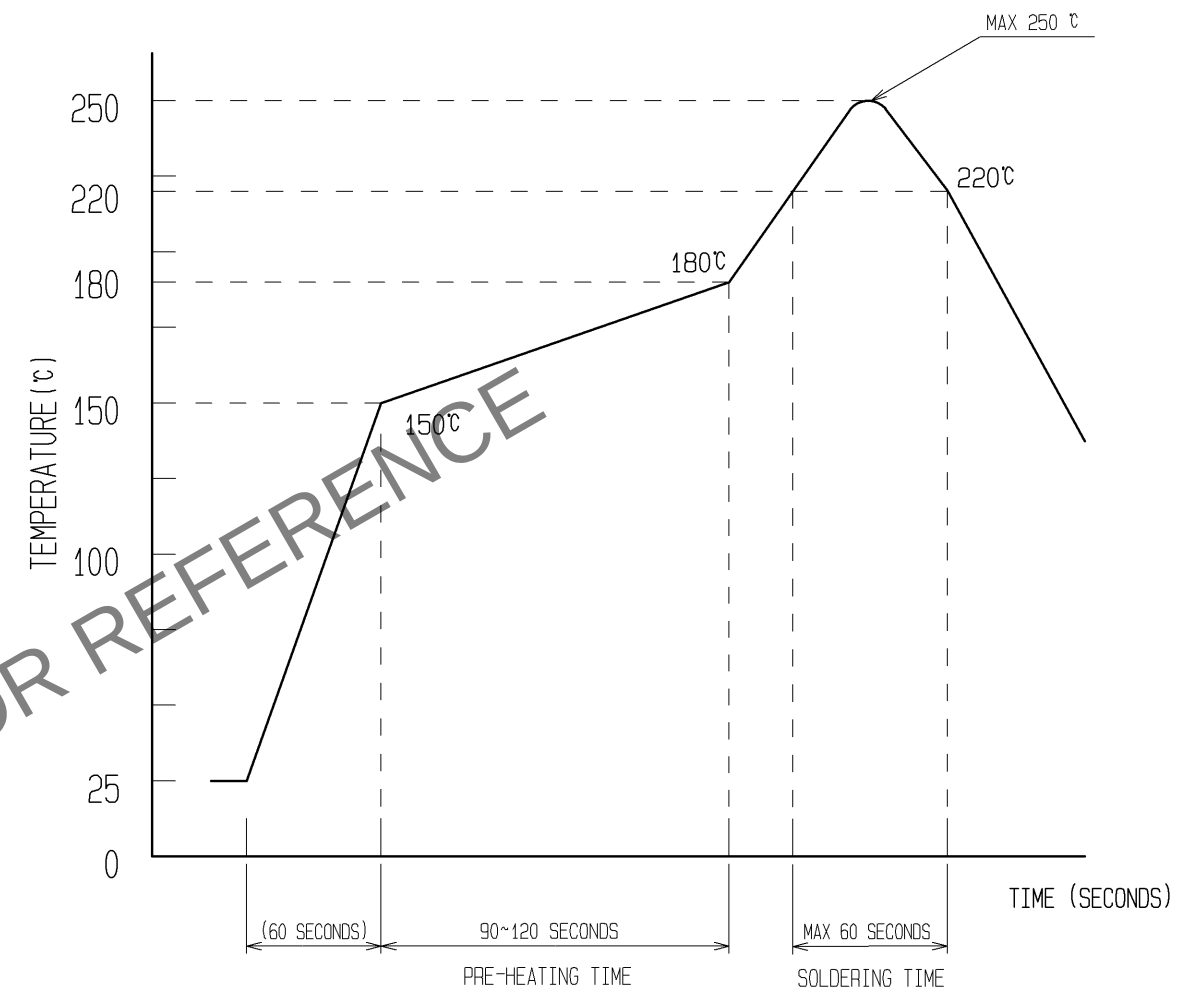
◆ RECOMMENDED METAL MASK DIMENSIONS

METAL MASK THICKNESS : $100 \mu\text{m}$



PART No.	Q
BM14B(0.8)-20DS-0.4V(52)	3.6
BM14B(0.8)-22DS-0.4V(52)	4.0
BM14B(0.8)-24DS-0.4V(52)	4.4
BM14B(0.8)-30DS-0.4V(52)	5.6
BM14B(0.8)-34DS-0.4V(52)	6.4
BM14B(0.8)-40DS-0.4V(52)	7.6
BM14B(0.8)-50DS-0.4V(52)	9.6

6 RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



REFLOW METHOD: IR REFLOW
NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.

- 1) REFLOW TIME
DURATION ABOVE 220 $^{\circ}\text{C}$, 60 SEC. MAX.
(PEAK TEMPERATURE: 250 $^{\circ}\text{C}$ MAX)
- 2) PRE-HEAT TIME
PRE-HEAT TEMPERATURE(MIN): 150 $^{\circ}\text{C}$
PRE-HEAT TEMPERATURE(MAX): 180 $^{\circ}\text{C}$
PRE-HEAT TIME: 90-120 sec.

6 THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE.
ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND
OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE, THEREFORE,
A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED
PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

HRS

DRAWING NO.	EDC3-322327-01
PART NO.	BM14B(0.8)-*DS-0.4V(52)
CODE NO.	CL684

